

英飞凌汽车级100V 175°C N沟道
增强型OptiMOS™ 5 功率晶体管

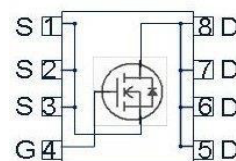
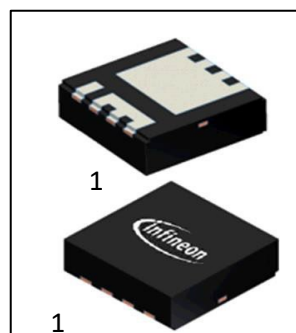
特点

- 适用于汽车应用的功率MOSFET
- N 沟道 - 增强型 - 逻辑电平
- 通过 AEC-Q101 认证
- MSL1 回流焊峰值温度高达 260°C
- 工作温度 175°C
- 绿色产品：符合 RoHS 标准
- 100% 雪崩测试
- 可进行自动光学检测 (AOI)

Type	Package	Marking
IAUZ18N10S5L420	PG-TSDSON-8	5N1L420

产品概述

V_{DS}	100	V
$R_{DS(on),max}$	42	mΩ
I_D	18	A

PG-TSDSON-8


除非另有规定，否则均为 $T_J=25^\circ\text{C}$ 的**最大额定值**。

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$T_C=25^\circ\text{C}, V_{GS}=10\text{V}$	18	A
		$T_C=100^\circ\text{C}, V_{GS}=10\text{V}^{1)}$	13	
		$T_C=25^\circ\text{C}$	72	
Pulsed drain current ¹⁾	$I_{D,pulse}$	$T_C=25^\circ\text{C}$	72	
Avalanche energy, single pulse ¹⁾	E_{AS}	$I_D=7\text{A}$	11	mJ
Avalanche current, single pulse	I_{AS}	-	7	A
Gate source voltage	V_{GS}	-	± 20	V
Power dissipation	P_{tot}	$T_C=25^\circ\text{C } T_J=175^\circ\text{C}$	30	W
Operating and storage temperature	T_j, T_{stg}	-	-55 ... +175	°C
IEC climatic category; DIN IEC 68-1	-	-	55/175/56	-

本数据手册的原文使用英文撰写。为方便起见，英飞凌提供了译文；由于翻译过程中可能使用了自动化工具，英飞凌不保证译文的准确性。为确认准确性，请务必访问 infineon.com 参考最新的英文版本（控制文档）。

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

热特性¹⁾

Thermal resistance, junction - case	R_{thJC}	-	-	-	5.0	K/W
Thermal resistance, junction - ambient	R_{thJA}	6 cm ² cooling area ²⁾	-	-	62	

除非另有规定，否则均为 $T_j=25^\circ\text{C}$ 的**电气特性**。

静态参数特性

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=1\text{mA}$	100	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=8\mu\text{A}$	1.2	1.7	2.2	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V, T_j=25^\circ\text{C}$	-	-	1	μA
		$V_{DS}=100V, V_{GS}=0V, T_j=125^\circ\text{C}^{1)}$	-	-	100	
Gate-source leakage current	I_{GSS}	$V_{GS}=20V, V_{DS}=0V$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=9A$	-	46	55	m Ω
		$V_{GS}=10V, I_D=9A$	-	34.5	42	
Gate resistance ¹⁾	R_G		-	1.8	-	Ω

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

动态参数特性¹⁾

Input capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=50V,$ $f=1MHz$	-	356	470	pF
Output capacitance	C_{oss}		-	68	88	
Reverse transfer capacitance	C_{rss}		-	6	9	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=50V, V_{GS}=10V,$ $I_D=18A, R_G=3.5\Omega$	-	1	-	ns
Rise time	t_r		-	1	-	
Turn-off delay time	$t_{d(off)}$		-	3	-	
Fall time	t_f		-	3	-	

门极电荷特点¹⁾

Gate to source charge	Q_{gs}	$V_{DD}=50V, I_D=9A,$ $V_{GS}=0 \text{ to } 10V$	-	1.2	1.7	nC
Gate to drain charge	Q_{gd}		-	1.2	2.0	
Gate charge total	Q_g		-	5.4	8	
Gate plateau voltage	$V_{plateau}$		-	3.3	-	V

反向二极管

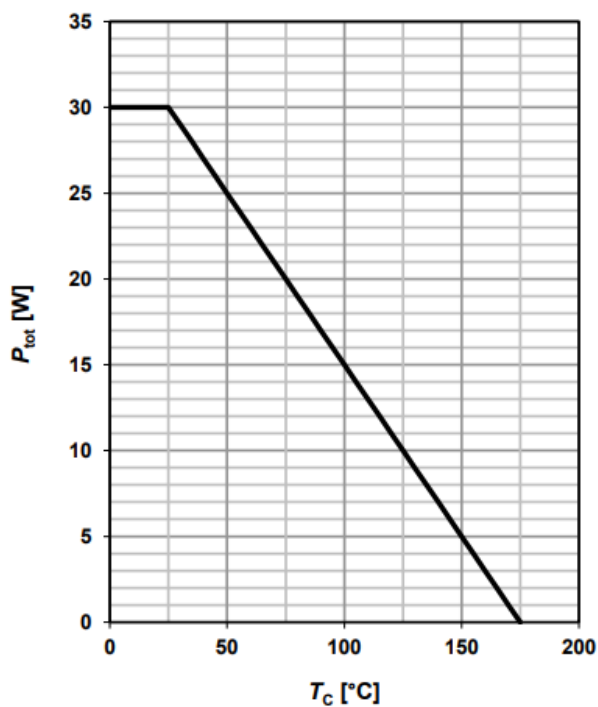
Diode continuous forward current ¹⁾	I_S	$T_C=25^\circ C$	-	-	18	A
Diode pulse current	$I_{S,pulse}$		-	-	72	
Diode forward voltage	V_{SD}	$V_{GS}=0V, I_F=9A,$ $T_J=25^\circ C$	-	0.9	1.1	V
Reverse recovery time ¹⁾	t_{rr}	$V_R=50V, I_F=18A,$ $di_F/dt=100A/\mu s$	-	36	-	ns
Reverse recovery charge ¹⁾	Q_{rr}		-	33	-	nC

¹⁾由设计标定，不受制于生产测试。

²⁾器件安装在 40 mm x 40 mm x 1.5 mm 环氧树脂印刷电路板 FR4 上，漏极连接用铜面积为 6 cm²（一层，70 μm 厚）。印刷电路板垂直放置在静止空气中。

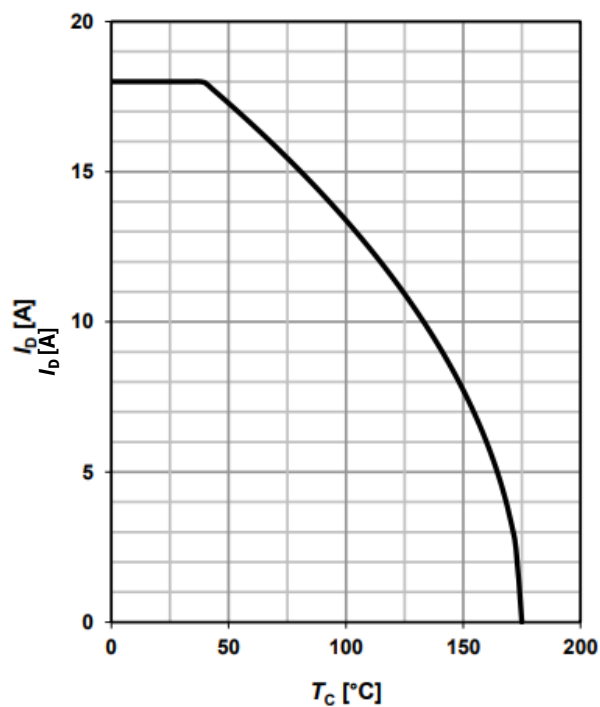
1 功率耗散

$$P_{\text{tot}} = f(T_c); V_{\text{GS}} \geq 6 \text{ V}$$



2 漏极电流

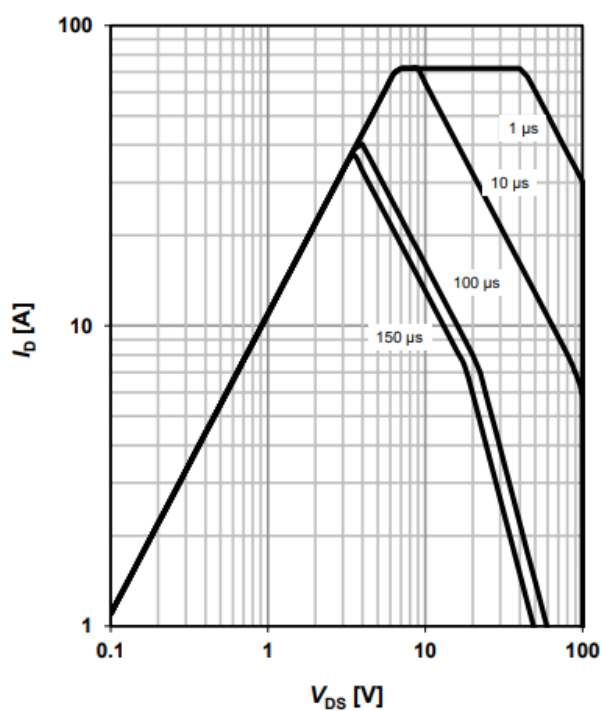
$$I_D = f(T_c); V_{\text{GS}} \geq 6 \text{ V}$$



3 安全工作区

$$I_D = f(V_{\text{DS}}); T_c = 25^\circ\text{C}; D = 0$$

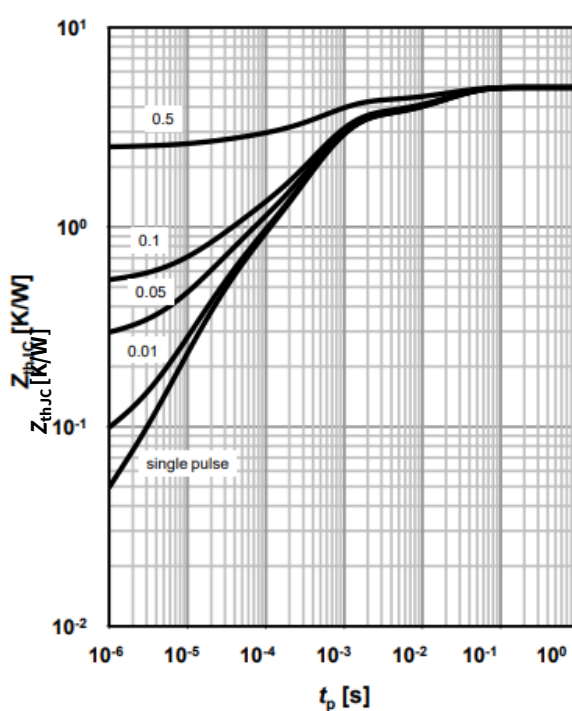
parameter: t_p



4 最大瞬态热阻抗

$$Z_{\text{thJC}} = f(t_p)$$

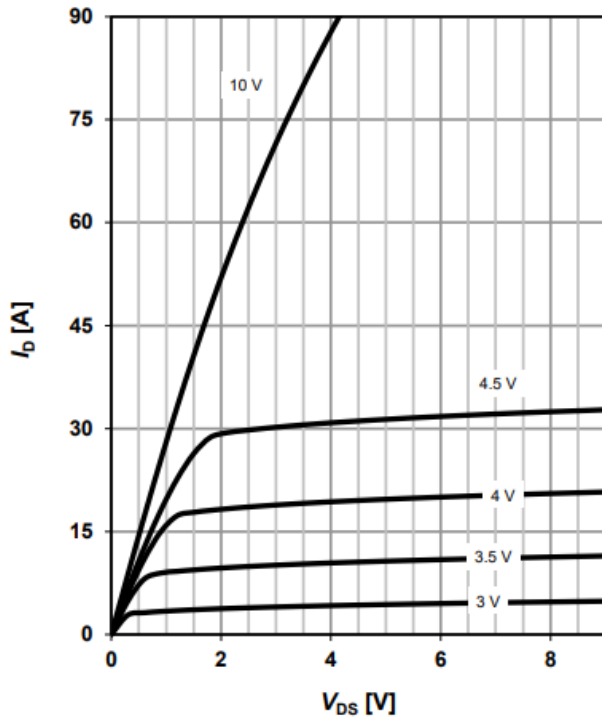
parameter: $D = t_p/T$



5 典型输出特性

$$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$$

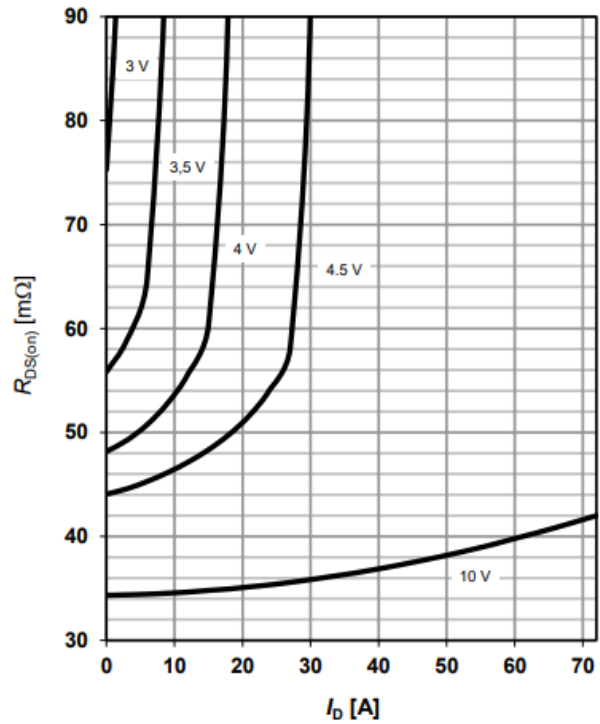
parameter: V_{GS}



6 典型漏源导通电阻

$$R_{DS(on)} = f(I_D); T_j = 25^\circ\text{C}$$

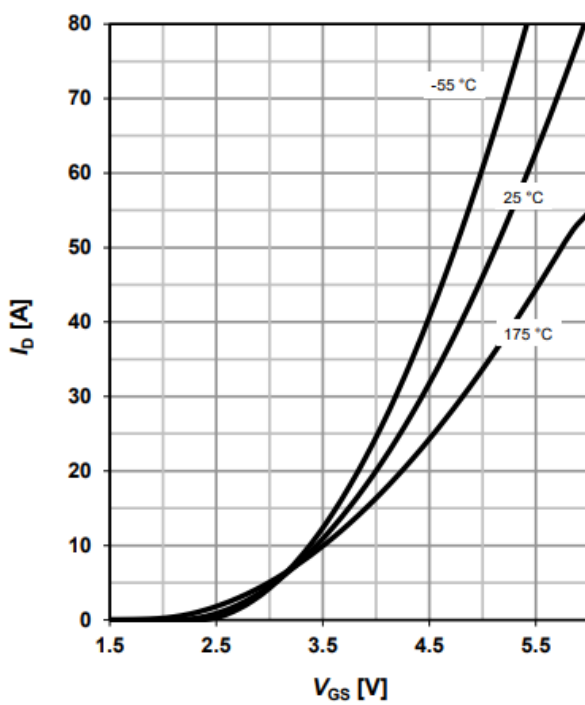
parameter: V_{GS}



7 典型转移特性

$$I_D = f(V_{GS}); V_{DS} = 6\text{V}$$

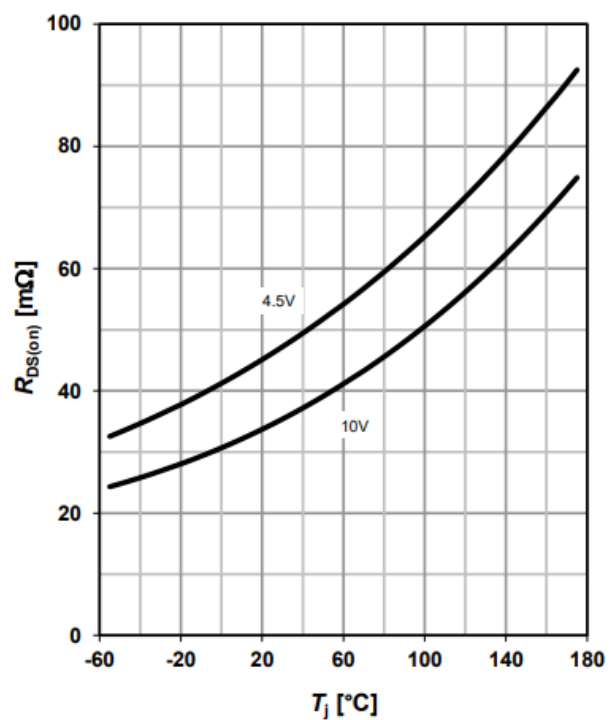
parameter: T_j



8 典型漏源导通电阻

$$R_{DS(on)} = f(T_j); I_D = 9\text{A}$$

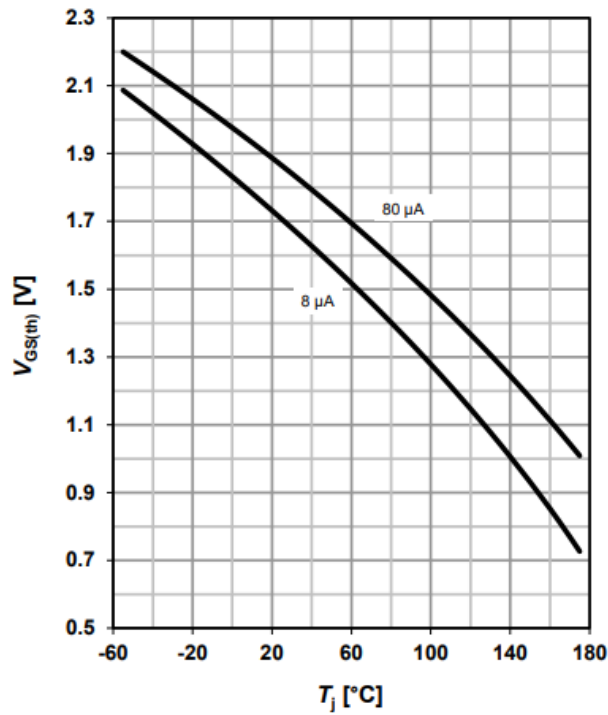
Parameter: V_{GS}



9 典型栅极阈值电压

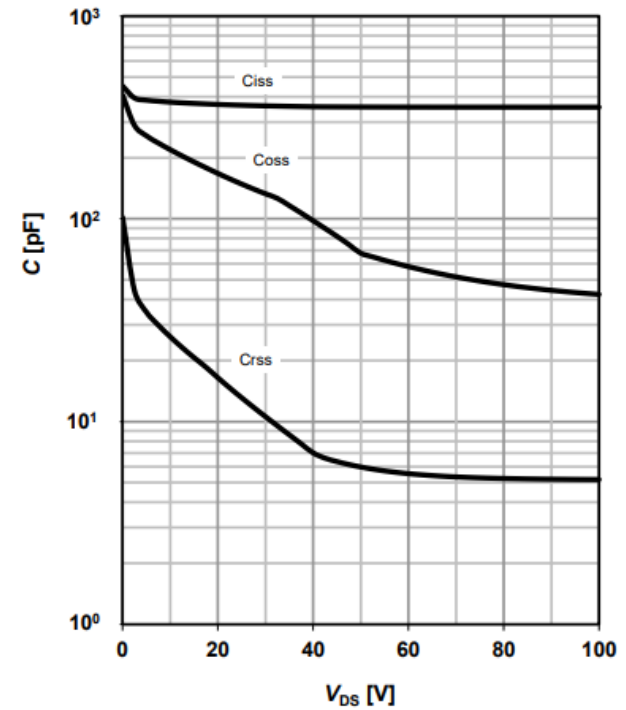
$$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$$

parameter: I_D



10 典型电容值

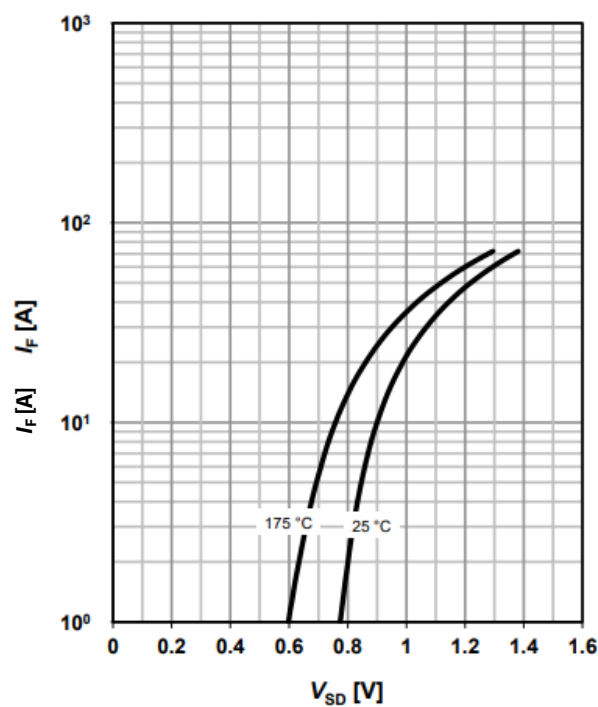
$$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$$



11 典型二极管正向导通特性

$$I_F = f(V_{SD})$$

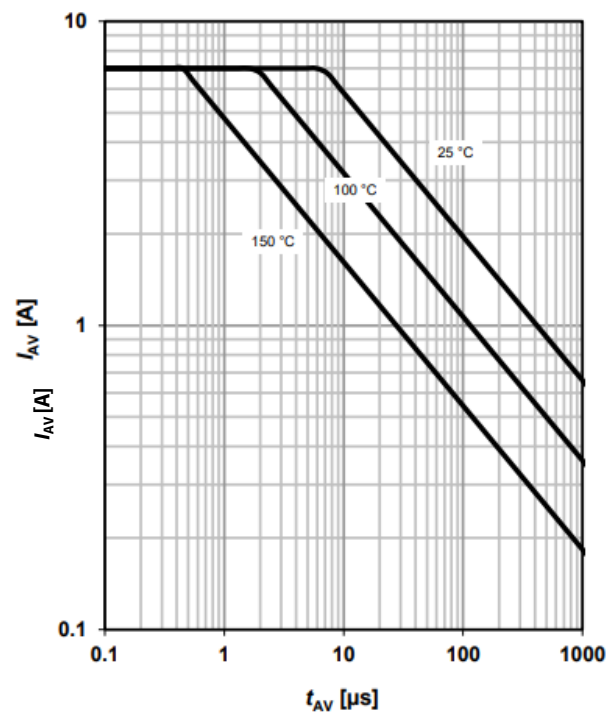
parameter: T_j



12 典型雪崩特性

$$I_{AS} = f(t_{AV})$$

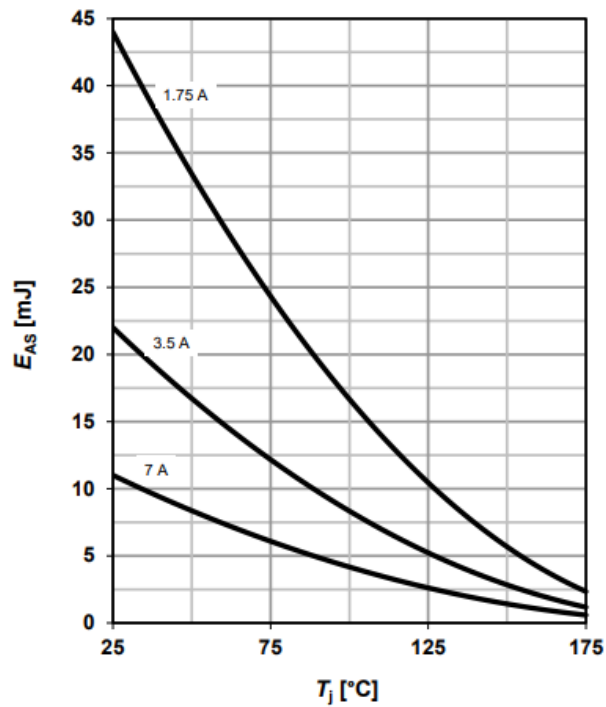
parameter: $T_{j(start)}$



13 典型雪崩能量

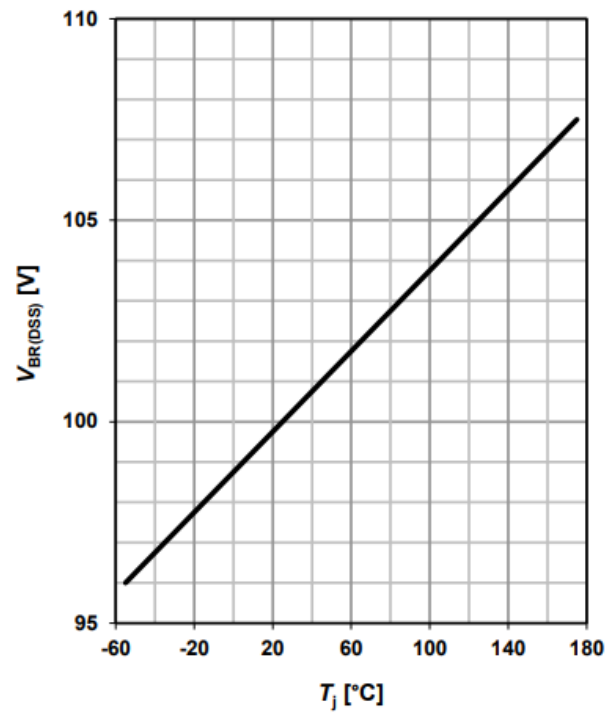
$$E_{AS} = f(T_j)$$

parameter: I_D



14 漏源击穿电压

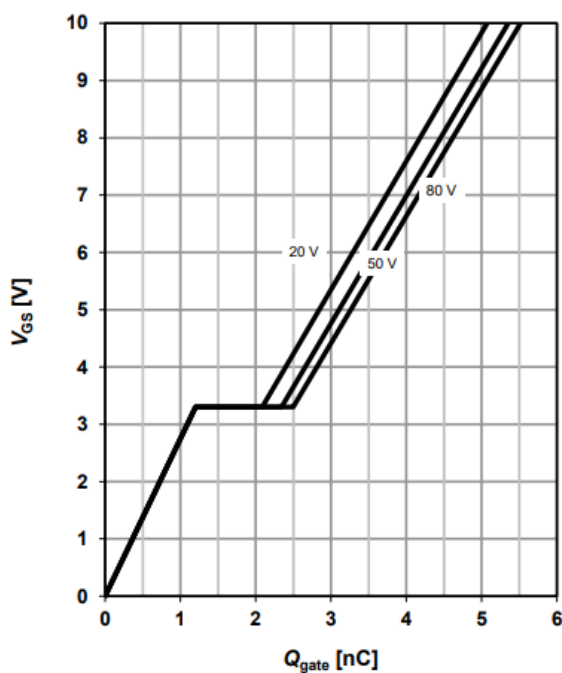
$$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$$



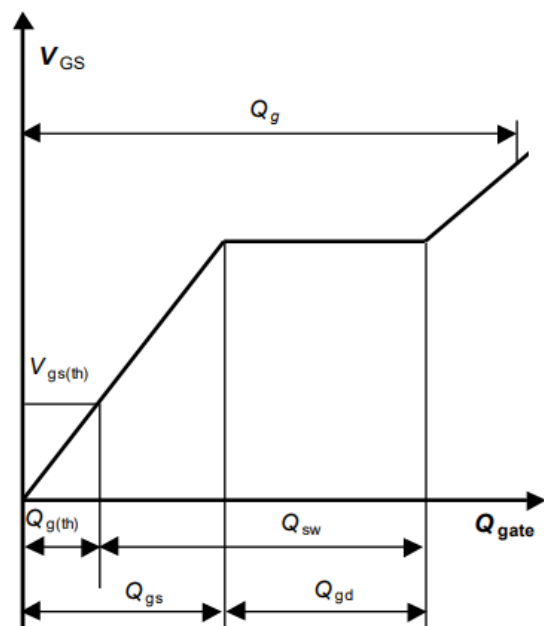
15 典型栅极电荷

$$V_{GS} = f(Q_{gate}); I_D = 9 \text{ A pulsed}$$

parameter: V_{DD}



16 栅极充电波形



[illegible]

Figure 1: Dimensions of the PCB layout. The figure consists of two parts: (a) Top view and (b) Side view. Part (a) shows a top view of the PCB with dimensions in inches. The overall dimensions are 2.29 inches by 2.36 inches. The copper layer is shown in solid gray, the solder mask in diagonal lines, and the stencil apertures in cross-hatching. Part (b) shows a side view of the PCB with dimensions in inches. The thickness of the PCB is 0.0625 inches. The dimensions of the copper layer, solder mask, and stencil apertures are also shown.

PIN 1
INDEX MARKING

8

12

3.6

0.3

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Revision History

Version	Date	Changes
Revision 1.0	23.07.2019	Final Data Sheet



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